



DATE: 9th June, 2021

PCN #: 2527

PCN Title: Additional Wafer Sources (GFAB, JK FAB), New Bill of Materials (BOM) with PdCu Bond Wire, and Additional Assembly/Test Site (CAT)

Dear Customer:

This is an announcement of change(s) to products that are currently being offered by Diodes Incorporated.

We request that you acknowledge receipt of this notification within 30 days of the date of this PCN. If you require samples for evaluation purposes, please make a request within 30 days as well. Otherwise, samples may not be built prior to this change. Please refer to the implementation date of this change as it is stated in the attached PCN form. Please contact your local Diodes sales representative to acknowledge receipt of this PCN and for any sample requests.

The changes announced in this PCN will not be implemented earlier than 90 days from the notification date stated in the attached PCN form.

Previously agreed upon customer specific change process requirements or device specific requirements will be addressed separately.

For questions or clarification regarding this PCN, please contact your local Diodes sales representative.

Sincerely,

Diodes Incorporated PCN Team



PRODUCT CHANGE NOTICE

PCN-2527 REV 1

Notification Date:	Implementation Date:	Product Family:	Change Type:	PCN #:
9 th June, 2021	9 th September, 2021	Analog Semiconductors	Qualified Additional FAB, BOM, A/T Site	2527
TITLE				
Additional Wafer Source (GFAB, JK FAB), New Bill of Materials (BOM) with PdCu Bond Wire, and Additional Assembly/Test (A/T) Site (CAT)				
DESCRIPTION OF CHANGE				
<p>This PCN is being issued to notify customers that in order to assure continuity of supply, Diodes has qualified two additional internal wafer sources (GFAB) located in Greenock, Scotland and (JK FAB) located in HsinChu, Taiwan, and new bill of materials (BOM) with PdCu bond wire. Some of these devices will also include an additional Diodes internal A/T site (CAT) located in Chengdu, China as noted in Table 3.</p> <p>Full electrical characterization and high reliability testing has been completed on representative part numbers to ensure no change to device functionality or electrical specifications in the datasheet. Refer to the attached qualification report embedded in this file (to view, download this PCN file then open it with a PDF viewer to see the attached qual report).</p>				
IMPACT				
Continuity of Supply. There will be no change to the Form, Fit or Function of products affected, unless specifically indicated. No change in datasheet parameters and product performance.				
PRODUCTS AFFECTED				
Table 1 - Qualified Additional Wafer Source (GFAB) Table 2 - Qualified Additional Wafer Source (GFAB), Additional (BOM) to Include PdCu Bond Wire Table 3 - Qualified Additional Wafer Source (GFAB), Additional A/T Site (CAT), Additional (BOM) to Include PdCu Bond Wire Table 4 - Qualified Additional Wafer Source (JK FAB), Additional (BOM) to Include PdCu Bond Wire Table 5 - Qualified Additional Wafer Source (JK FAB)				
WEB LINKS				
Manufacturer's Notice:	https://www.diodes.com/quality/product-change-notices/diodes-product-change-notices/			
For More Information Contact:	https://www.diodes.com/about/contact-us/contact-sales/			
Data Sheet:	http://www.diodes.com/products/			
DISCLAIMER				
Unless a Diodes Incorporated Sales representative is contacted in writing within 30 days of the posting of this notice, all changes described in this announcement are considered approved.				

Table 1 - Qualified Additional Wafer Source (GFAB)

AP4310EMTR-AG1	AP4310EMTR-G1	AS339AMTR-E1	AS339AMTR-G1	AS339AP-E1	AS358AGTR-G1
AS358AP-E1	AS358GTR-E1	AS358MMTR-G1	AS393AP-E1	AS393GTR-E1	AS393MMTR-G1

Table 2 - Qualified Additional Wafer Source (GFAB), Additional (BOM) to Include PdCu Bond Wire

AS321KTR-E1	AS321KTR-G1	AS324AMTR-E1	AS324AMTR-G1	AS324GTR-E1	AS324GTR-G1
AS324MTR-E1	AS324MTR-G1	AS339GTR-E1	AS339GTR-G1	AS339MTR-E1	AS339MTR-G1
AS358AMTR-E1	AS358MTR-E1	AS358MTR-G1	AS393MTR-E1	AS393MTR-G1	LM2901AS14-13
LM2901AT14-13	LM2901S14-13	LM2901T14-13	LM2902AS14-13	LM2902AT14-13	LM2902S14-13
LM2902T14-13	LM2903ATH-13	LM2903TH-13	LM2904ATH-13	LM2904TH-13	

Table 3 - Qualified Additional Wafer Source (GFAB), Additional A/T Site (CAT), Additional (BOM) to Include PdCu Bond Wire

AS358AMTR-G1	AS393AMTR-E1	AS393AMTR-G1	LM2903AM8-13	LM2903AS-13	LM2903M8-13
LM2903S-13	LM2904AM8-13	LM2904AS-13	LM2904M8-13	LM2904S-13	

Table 4 - Qualified Additional Wafer Source (JKFAB), Additional (BOM) to Include PdCu Bond Wire

AS339GTR-E1	AS339GTR-G1	AS339MTR-E1	AS339MTR-G1	LM2901AS14-13	LM2901AT14-13
LM2901S14-13	LM2901T14-13				

Table 5 - Qualified Additional Wafer Source (JKFAB)

AH211Z4-AG1	AH277AZ4-AG1	AP2202K-3.0TRG1	AP2210K-2.8TRE1	AP2210N-2.8TRG1	AP2213H-2.5TRG1
AH211Z4-BG1	AH277AZ4-BG1	AP2202K-3.3TRE1	AP2210K-2.8TRG1	AP2210N-3.0TRE1	AP2213H-3.3TRG1
AH266Z4-AG1	AH277AZ4-CG1	AP2202K-3.3TRG1	AP2210K-3.0TRE1	AP2210N-3.0TRG1	AP4310EMTR-AG1
AH266Z4-BG1	AP2202K-2.5TRE1	AP2202K-5.0TRG1	AP2210K-3.0TRG1	AP2210N-3.3TRE1	AP4310EMTR-G1
AH266Z4-CG1	AP2202K-2.5TRG1	AP2202K-ADJTRE1	AP2210K-3.3TRE1	AP2210N-3.3TRG1	AS339AMTR-E1
AH276Z4-AG1	AP2202K-2.6TRE1	AP2202K-ADJTRG1	AP2210K-3.3TRG1	AP2210N-3.6TRG1	AS339AMTR-G1
AH276Z4-AG1-01	AP2202K-2.6TRG1	AP2202R-3.3TRE1	AP2210K-5.0TRG1	AP2210N-4.0TRG1	AS339AP-E1
AH276Z4-AG1-F	AP2202K-2.8TRE1	AP2202R-3.3TRG1	AP2210K-ADJTRG1	AP2210N-5.0TRG1	
AH276Z4-BG1	AP2202K-2.8TRG1	AP2210K-2.5TRE1	AP2210N-2.5TRE1	AP2213D-3.3E1	
AH276Z4-CG1	AP2202K-3.0TRE1	AP2210K-2.5TRG1	AP2210N-2.8TRE1	AP2213D-3.3TRE1	